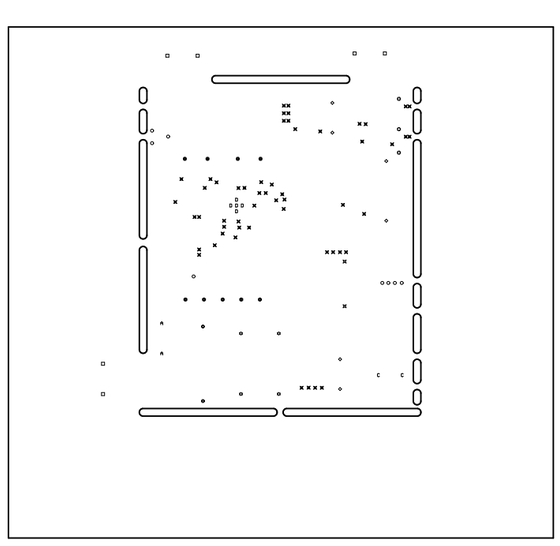
Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.40mil	3.5	
1	Top Layer		1.40mil		
	Dielectric 1	FR-4	8.00mil	4.2	
2	Signal Layer 1		1.40mil		
	Dielectric 2	FR-4	18.00mil	4.2	
3	Signal Layer 2		1.40mil		
	Dielectric 3	FR-4	8.00mil	4.2	
4	Bottom Layer		1.40mil		
	Bottom Solder	Solder Resist	0.40mil	3.5	
	Bottom Overlay				



1000.00mil

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
D	5	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
○	8	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
✕	54	11.81mil (0.300mm)	PTH	Round	Top Layer - Bottom Layer	
C	2	25.59mil (0.650mm)	PTH	Round	Top Layer - Bottom Layer	
◇	6	33.47mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
◉	2	35.43mil (0.900mm)	PTH	Round	Top Layer - Bottom Layer	
⌑	2	37.40mil (0.950mm)	PTH	Round	Top Layer - Bottom Layer	
✚	9	39.37mil (1.000mm)	PTH	Round	Top Layer - Bottom Layer	
A	2	41.34mil (1.050mm)	PTH	Round	Top Layer - Bottom Layer	
□	6	49.21mil (1.250mm)	PTH	Round	Top Layer - Bottom Layer	
☼	4	53.15mil (1.350mm)	PTH	Round	Top Layer - Bottom Layer	
✪	3	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
	103 Total					

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 40.4 MIL (1.0mm) +/-10% [ ] OTHER 40MIL
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
[ ] XX MIL VIAS REQUIRE NON-CONDUCTIVE FILL AND PLANARIZE
[ ] XX MIL VIAS REQUIRE CONDUCTIVE FILL AND PLANARIZE
[ ] OUTER XX MIL VIAS REQUIRE 50 OHM SINGLE-ENDED IMPEDANCE
[ ] LAYER 2 & 3 (INNER LAYERS) XX MIL WIDE, XX MIL SPACE TRACES REQUIRE 100 OHM DIFFERENTIAL IMPEDANCE

TEXAS INSTRUMENTS

PROJECT TITLE: ZVS Aux Flyback
DESIGNED FOR: Public Release
FILE NAME: PMP23195.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP23195	REV: A	SVN REV: Not in version control
LAYER NAME = [illegible]ions	TID #: N/A		
PLOT NAME = Fabrication Drawing	GENERATED : 7/29/2022 12:55:42 PM	TEXAS INSTRUMENTS	

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ENGINEER:	LAYOUT BY:
Ben Lough	Ben Lough
SCALE: 1.00	ALTIUM DESIGNER VERSION: 21.2.2.38